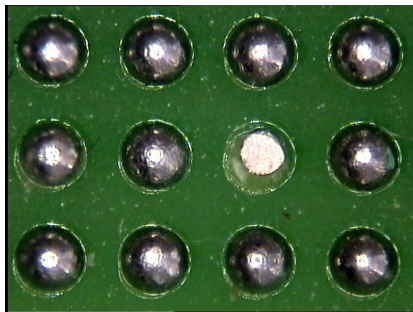


ScanINSPECT BPI™

"Ball Placement Inspection"



0.3 mm balls

WHAT IS ScanINSPECT?

ScanINSPECT provides a simple and user-friendly alternative to inaccurate and time-consuming manual inspection methods or expensive high-end AOI systems.

ScanINSPECT uses a simple Windows user interface integrated with an image-processing unit. This combination allows 100% inspection of ball or bump placement on a wide variety of substrates and device types including FR4, Ceramic, Wafer, Flip chip, BGA, CSP, etc. The system can be used either pre or post reflow.

HOW DOES ScanINSPECT WORK?

ScanINSPECT's integration within the production environment provides inspection of ball or bump:

- Presence/Absence
- Size
- Position

Each device or substrate is placed into ScanINSPECT for 100% inspection. The balls or bumps are inspected and any errors are displayed on the screen. No more surprises!

FAST & SIMPLE PROGRAMMING

ScanINSPECT is quickly programmed from a golden part in a few minutes. Corrections to the golden part can be quickly and easily made, if necessary.

INCREASE YIELD & IMPROVE OVERALL EQUIPMENT EFFICIENCY

ScanINSPECT's powerful 100% inspection process increases product yield by ensuring accurate ball or bump placement. Missing balls or bumps can result in reduced yield, lost production time and extensive rework.

Missing or misplaced balls or bumps are now automatically detected. Problems are identified and eliminated before substrates or devices are reflowed, permitting quick and easy rework.

SIMPLICITY

ScanINSPECT set up is fast and easy. In production, each device or substrate is placed on the table, shuttled in, automatically aligned and checked for accuracy with a PASS or FAIL inspection in seconds.

WHY USE ScanINSPECT?

- **Mandatory:** 100% automatic inspection of ball or bump placement, pre and/or post reflow.
- **Security:** Confirm ball/bump absence / presence.
- **Necessity:** Detect errors before reflow permitting easy rework.
- **Flexibility:** System is tailored to meet specific customer's requirements.



DESKTOP MODULE

System Specifications*

- Maximum Substrate Size: 18" X 24" (457mm X 610mm)
- Maximum Inspection Area: 11.7" X 16.5" (297mm X 419mm)
- Ball/Bump Diameter Range: 0.050 mm to 6 mm
- Resolution: 400/1000/2000/3200*/4000* dpi
- *Reduced Inspection area for 3200 & 4000 dpi.

Footprint of Inspection Unit

- Depth: 31.5" (800mm), table extended 49.5" (1,257mm)
- Width: 27.25" (692mm)
- Height: 19" (482mm)
- Weight: 150lbs. (55.95kg)

COMPUTER*

- Pentium (3GHz or higher) Personal Computer
- 80 GB HD, 2 GB RAM
- CD-ROM (CD-RW for archive purposes)
- Monitor
- Printer
- Win XP Service Pack 2
- 2 available USB ports
- *Recommended customer supplied minimum PC requirements.

(All specifications and designs subject to change without notice.)



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